L Number	Hits	Search Text	DB	Time stamp
-	595	438/455	USPAT;	2002/04/17 08:34
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-	190	438/456	USPAT;	2002/04/11 16:23
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_	546	438/977	USPAT;	2002/04/17 08:31
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			DERWENT;	
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-	110	148/135	USPAT;	2002/04/11 16:23
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			IBM TDB	
_	267	148/12	USPAT;	2002/04/11 07:26
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			DERWENT;	
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_	276	257/254	USPAT;	2002/04/12 14:12
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	107	257/74	IBM_TDB USPAT;	2002/04/12 14:12
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-	305	438/50	USPĀT;	2002/04/17 13:36
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j			DERWENT;	
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-	249	438/51	USPAT; US-PGPUB;	2002/04/12 14:14
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-	361	438/52	USPAT;	2002/04/12 14:14
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-	537	438/53	USPAT;	2002/04/12 14:14
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			DERWENT;	
			IBM TDB	
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			DERWENT;	
			IBM_TDB	
-	256	437/132	USPAT;	2002/04/17 13:21
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_	1292	437/67	USPAT;	2002/04/12 14:16
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	ļ		DERWENT;	
			IBM TDB	
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			,	
-	283	437/86	USPAT;	2002/04/17 16:21
			US-PGPUB;	
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			IBM TDB	
l _	366	257/528	USPAT;	2002/04/15 07:54
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-	71	438/457	USPAT;	2002/04/15 15:17
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			DERWENT;	
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-	512	438/460	USPAT;	2002/04/15 15:19
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_	1061	438/118	USPAT;	2002/04/17 10:48
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-	356	438/406	USPĀT;	2002/04/16 18:52
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_	2052	438/622	USPAT;	2002/04/17 08:36
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-	50	438/118 and bonding and (three adj layer)	USPAT;	2002/04/17 09:31
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			EPO; JPO;	
			DERWENT;	
1	1		IBM_TDB	

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C:\APPS\east\workspaces\A Method For Forming A semiconductor Device And It Formed by a Method.wsp

-	36	438/622 and bonding and (three adj layer)	USPAT; US-PGPUB; EPO; JPO;	2002/04/17 09:25
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-	77	257/758 and bonding and (three adj layer)	USPAT; US-PGPUB;	2002/04/17 10:57
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-	171	257/622 and bonding	IBM_TDB USPAT; US-PGPUB;	2002/04/17 10:58
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-	582	257/758 and bonding	IBM_TDB USPAT; US-PGPUB;	2002/04/17 11:59
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_	3	micro-opto-electro-mechanical and (257/\$.ccls. or 438/\$.ccls.)	IBM_TDB USPAT; US-PGPUB;	2002/04/17 13:24
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_	4	(micro adj1 opto adj1 electro adj1 mechanical) and (257/\$.ccls. or	IBM_TDB USPAT; US-PGPUB;	2002/04/17 13:29
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-	7	437/67 and bonding and (three adj layer)	IBM_TDB USPAT; US-PGPUB;	2002/04/17 13:31
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_	2	437/132 and bonding and (three adj layer)	USPAT; US-PGPUB;	2002/04/17 13:32
			EPO; JPO; DERWENT; IBM TDB	
-	15	437/86 and bonding and (three adj layer)	USPAT; US-PGPUB;	2002/04/17 13:32
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-	49	437/132 and bonding	USPAT; US-PGPUB;	2002/04/17 13:35
			EPO; JPO; DERWENT; IBM TDB	
_	148	437/67 and bonding	USPĀT; US-PGPUB;	2002/04/17 13:35
			EPO; JPO; DERWENT; IBM TDB	
-	215	437/86 and bonding	USPĀT; US-PGPUB;	2002/04/17 13:36
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	132	438/50 and bonding	USPAT;	2002/04/17 13:37
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			DERWENT;	
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_	165	438/51 and bonding	USPĀT;	2002/04/17 13:37
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-	227	438/53 and bonding	USPAT;	2002/04/17 13:38
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			DERWENT;	
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			EPO; JPO; DERWENT;	
			IBM TDB	
			J IDM IVB	

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